

IN THE CLAIMS:

Please amend the claims as follows.

1. (Currently Amended) A multilayer circuit board, comprising:

a substrate having a first surface and a second surface extending from an end of

the first surface at a required angle relative to the first surface;

a multilayer circuit formed on the first surface of said substrate and composed of a

plurality of circuit layers, each of which is provided with a conductive

layer having a required circuit pattern and an insulation layer formed on

said conductive layer by film formation;

a second conductive layer formed on the second surface of said substrate, by

which said conductive layer of one of said circuit layers is electrically

connected to said conductive layer of another one of said circuit layers,

wherein the second surface of said substrate includes a side surface of a

projection on the first surface,

wherein the first surface ~~is a top surface of said substrate~~ is a higher level surface

than a level surface of the second surface of said substrate, and the second

surface further includes a side surface of said substrate, and

wherein the required angle between the first and second surfaces is an obtuse

angle.
- 2.-4. (canceled)
5. (Currently Amended) ~~A The multilayer circuit board, comprising:~~ set forth in
claim 1, wherein said multilayer circuit has an aperture, through which a part of the first

surface is exposed, and an electronic device is mounted in a concave formed in the exposed first surface, and an electrical connection between said multilayer circuit and said electronic device is made by a third conductive layer formed on an inner surface of said concave.

~~a substrate having a first surface and a second surface extending from an end of the first surface at a required angle relative to the first surface;~~
~~a multilayer multilayer circuit formed on the first surface of said substrate and composed of a plurality of circuit layers, each of which is provided with a conductive layer having a required circuit patter pattern and an insulation layer formed on said conductive layer by film formation;~~
~~a second conductive layer formed on the second surface of said substrate, by which a layer to layer connection of said multilayer circuit is made, wherein said multilayer circuit has an aperture, through which a part of the first surface is exposed, and an electronic device is mounted in a concave formed in the exposed first surface, and an electrical connection between said multilayer circuit and said electronic device is made by a third conductive layer formed on an inner surface of said concave.~~
~~wherein the first surface is a top surface of said substrate, and the second surface further includes a side surface of said substrate, and~~
~~wherein the required angle between the first and second surfaces is an obtuse angle.~~

6. (Currently Amended) The multilayer circuit board as set forth in claim 1, wherein said second conductive layer is a plurality of second conductive layers ~~to obtain plural~~

~~layer to layer connections of said multilayer circuit, by each of which said conductive~~
~~layer of one of said circuit layers is electrically connected to said conductive layer of~~
~~another one of said circuit layers, and each of said second~~ conductive layers is separated
from an adjacent second conductive layer in the thickness direction by a second
insulation layer.

7. (Currently Amended) A multilayer circuit board, comprising:

- a substrate having a first surface and a second surface extending from an end of
the first surface ~~at a required angle relative to the first surface~~ at an obtuse
angle relative to the first surface, the second surface further including a
side surface of a projection on the first surface, a side surface of said
substrate and a level surface, and the first surface being a higher level
surface than the level surface of the second surface of said substrate;
- a multilayer circuit formed on the first surface of said substrate and composed of a
plurality of circuit layers, each of which is provided with a conductive
layer having a required circuit pattern and an insulation layer formed on
said conductive layer by film formation;
- ~~a second conductive layer formed on the second surface of said substrate, by~~
~~which a layer to layer connection of said multilayer circuit is made,~~
~~wherein said substrate has a third surface extending at a different level~~
~~from the first surface and a fourth surface extending from the other end of~~
~~the first surface to an end of the third surface, and said multilayer circuit is~~
~~formed on the first, third, and fourth surfaces of said substrate, and said~~
~~second conductive layer is formed on the second surface that is a side~~

~~surface of a projection on the first surface to make the layer-to-layer connection of said multilayer circuit, for electrically conducting said conductive layer of one of said circuit layers to said conductive layer of another one of said circuit layers, wherein when said multilayer circuit is on the first surface, said conductive layer of one of said circuit layers is electrically connected to said conductive layer of another one of said circuit layers by said second conductive layer on the side surface of said projection as the second surface; and~~

when said multilayer circuit is on the level surface of the second surface of said substrate, said conductive layer of one of said circuit layers is electrically connected to said conductive layer of another one of said circuit layers by said second conductive layer on the second surface extending from the end of the first surface at an obtuse angle.

~~wherein the first surface is a top surface of said substrate, and the second surface further includes a side surface of said substrate, and wherein the required angle between the first and second surfaces is an obtuse angle.~~

8. (Currently Amended) A multilayer circuit board comprising:

a substrate having a first surface and a projection formed on the first surface, a side surface of said projection extending at an obtuse angle relative to the first surface;

a pair of multilayer circuits formed on the first surface at both sides of said projection, each of said multilayer circuits composed of a plurality of

circuit layers, each of which is provided with a conductive-metal layer having a required circuit pattern and an insulation layer formed on said conductive-metal layer by film formation; and

a second conductive-metal layer successively formed on side and top surfaces of said projection,

wherein said conductive-metal layer of one of said circuit layers is electrically connected to said conductive layer of another one of said circuit layers by said second conductive-metal layer on the side surface of said projection, and simultaneously one of the pair of multilayer circuits is electrically connected to the other one by said second conductive-metal layer on the side and top surfaces of said projection,

~~wherein an angle between the side surface of said projection and the first surface is an obtuse angle.~~

9. (Previously Presented) The multilayer circuit board as set forth in claim 8, wherein said multilayer circuit has an aperture, through which a part of the first surface is exposed, and an electronic device is mounted in a concave formed in the exposed first surface, and an electrical connection between said multilayer circuit and said electronic device is made by a third conductive-metal layer formed on an inner surface of said concave.

10. (Previously Presented) The multilayer circuit board as set forth in claim 8, wherein said second conductive-metal layer is a plurality of second conductive layers to obtain plural layer-to-layer connections of said multilayer circuit, and each of second

conductive-metal layers is separated from an adjacent second conductive-metal layer in the thickness direction by a second insulation layer.

11. (Previously Presented) The multilayer circuit board as set forth in claim 8, comprising a third conductive-metal layer for forming another layer-to-layer connection of said multilayer circuit, which is formed on a side surface of said substrate extending adjacent to the first surface.

12. (New) The multilayer circuit board as set forth in claim 1, wherein said conductive layer of one of said circuit layers is electrically connected to said conductive layer of another one of said circuit layers by said second conductive layer on the side surface of said projection as the second surface.

13. (New) The multilayer circuit board as set forth in claim 1, wherein said conductive layer of one of said circuit layers is electrically connected to said conductive layer of another one of said circuit layers by said second conductive layer on the second surface extending from the end of the first surface at an obtuse angle.

14. (New) The multilayer circuit board as set forth in claim 1, wherein said conductive layer of one of said circuit layers is electrically connected to said conductive layer of another one of said circuit layers by said second conductive layer on the side surface of said substrate as the second surface.